

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method of assembling a semiconductor device and a lead frame, the lead frame having a plurality of lead fingers in strip form, each lead finger of the plurality of lead fingers having a bonding end, the plurality of lead fingers forming an opening for a semiconductor device, the lead frame having no die paddle for supporting the semiconductor device thereon, comprising:

adhesively attaching the segment of tape to portions of the lead frame, the segment of tape extending across the opening having [a thermosetting] adhesive located thereon forming [an] attachment locations [location] for the semiconductor device and for portions of the lead fingers of a lead frame;

attaching portions lead fingers of the plurality of lead fingers to a portion of the segment of tape;
and

attaching the semiconductor device to at least a portion of the segment of tape at the attachment location for the semiconductor device using the thermosetting adhesive located on a portion of the segment of tape, the semiconductor device having a portion thereof located within the opening formed by the plurality of lead fingers of the lead frame.

2. (Original) The method of claim 1, further including:
forming at least one aperture in the segment of tape.

3. (Original) The method of claim 1, further including:
forming a plurality of apertures in the segment of tape.

4. (Original) The method of claim 3, wherein the plurality of apertures substantially forms a grid-like pattern of apertures.

5. (Previously Presented) The method of claim 2, wherein the semiconductor device is attached to the segment of tape such that at least a portion of an outer periphery of the semiconductor device is adjacent to a portion of a periphery of the at least one aperture.

6. (Previously Presented) The method of claim 3, wherein the semiconductor device is attached to the segment of tape such that at least a portion of an outer periphery of the attachment surface of the semiconductor device is positioned within at least one aperture of the plurality of apertures.

7. (Original) The method of claim 1, further including:
wire bonding contacts of the semiconductor device to the bonding ends of the plurality of lead fingers.

8. (Original) The method of claim 1, further including:
packaging the semiconductor device in an encapsulating material to form a packaged semiconductor device.

9. (Original) The method of claim 8, further comprising:
forming the segment of tape to fit within the encapsulating material.

10. (Currently Amended) A method of assembling a semiconductor device and a lead frame, said lead frame having a plurality of lead fingers, each lead finger of the plurality of lead fingers having an end forming an opening between the ends of the plurality of lead fingers of the lead frame having a size of at least the attachment surface of the semiconductor device, comprising:
attaching at least two tape segments to portions of the lead frame, the at least two tape segments being spaced to define at least one opening between the at least two tape segments
providing an attachment location for the semiconductor device therein and portions of the plurality of lead fingers of the lead frame thereto, said at least two tape segments shaped

18. (Previously Presented) The method of claim 10, wherein the at least two tape segments comprises three or more tape segments.

19. (Previously Presented) The method of claim 10, further including forming at least one aperture in at least one tape segment of the at least two tape segments.

20. (Previously Presented) The method of claim 10, wherein the adhesively attaching the at least two tape segments to the portion of the ends of the plurality of lead fingers comprises spacing the at least two tape segments to define at least two openings between the at least two tape segments.